

AgilLink™ 2.50mm Wire-to-Board Header G863

CUSTOMIZABLE SHROUDED WIRE-TO-BOARD HEADER

AgilLink™ 2.50mm wire-to-board is the most common solution for transferring power and signal. This series can carry a maximum current rating of 1.25A to 3A. Amphenol ICC offers a comprehensive range of these headers including, vertical DIP, right angle DIP, vertical SMT and right angle SMT to meet various customer requirements. It comes with customizable pin length or latch which makes it an ideal choice for several applications and specific designs.

- Flexible and easy to change pin lengths to meet various application requirements
- Accommodates wire range from 28AWG to 22AWG
- Option for latch lock
- Supports PiP process
- Easy pin insertion and high retention force onto PCB



TARGET MARKETS



FEATURES

- Customizable pin length
- Various mounting options including vertical DIP, right angle DIP, vertical SMT and right angle SMT
- High temperature thermoplastic material
- Tape and reel packaging option
- RoHS compliant and halogen-free
- Latch option
- Mates with G863 and G883H/C wire-to-board headers

BENEFITS

- Suitable for different applications and specific designs
- Ease in choosing board mating configurations
- Reflow compatible
- Supports PiP process
- Meets environmental, health and safety requirements
- Easy mating and unmating
- Mutually compatible for wire-to-board

TECHNICAL INFORMATION

MATERIAL

- Housing: High temperature thermoplastic, UL94V-0
- Contact: Copper alloy, selective gold plating on contact area, 100µin tin plating on solder tail and 50µin nickel under-plated overall

MECHANICAL PERFORMANCE

- Contact Retention Force: Base on individual P/N
- Durability: 30 cycles
- Insertion Force: Base on individual P/N
- Withdrawal Force: Base on individual P/N
- Vibration: 1µs max., EIA 364-28
- Mechanical Shock: 1µs max., EIA 364-27

ELECTRICAL PERFORMANCE

- Current Rating: 1.25 to 3A AC/DC (base on individual P/N)
- Voltage Rating: 250V AC/DC
- Temperature: -40°C to +85°C
- Contact Resistance: 20mΩ max.
- Insulation Resistance: 1000MΩ min.

PACKAGING

- Tape and reel
- Bag

SPECIFICATION

- Amphenol Product Specification: GS-863

ENVIRONMENTAL

- Thermal shock:
 - a) -55°C to 30 minute
 - b) +85°C to 30 minute, 10 cycles, EIA 364-32
- Humidity: 40°C, 90 to 95%RH, 96 hours, EIA 364-31
- Heat Resistance : 85°C, 96 hours, EIA 364-17
- Cold Resistance: -40°C, 96 hours, EIA 364-17
- Solder-ability: 95% min. solder coverage, EIA 364-52
- Resistance to Soldering Heat: Peak temperature: 260°C max., 10 seconds max.

TARGET MARKETS/APPLICATIONS



Communications



Consumer



Server
Storage



Industrial & Instrumentation



Medical